

## Nch 30V 16A Middle Power MOSFET

## Datasheet

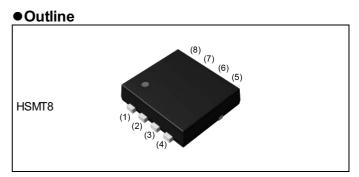
V <sub>DSS</sub>	30V
R <sub>DS(on)</sub> (Max.)	4.5mΩ
I <sub>D</sub>	±16A
P <sub>D</sub>	2W

## Features

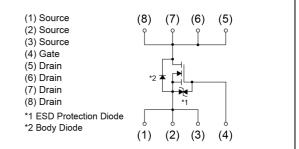
Application

Switching

- 1) Low on resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package.
- 4) Pb-free lead plating ; RoHS compliant



## Inner circuit



## Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Quantity (pcs)	3000
	Taping code	ТВ
	Marking	E160AD

## • Absolute maximum ratings (T<sub>a</sub> = 25°C, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	30	V
Continuous drain current	۱ <sub>D</sub>	±16	А
Pulsed drain current	I <sub>DP</sub> *2	±64	А
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	16	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	23	mJ
Power dissipation	P <sub>D</sub> <sup>*4</sup>	2	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## •Thermal resistance

Parameter	Symbol	Values			Linit
Falanielei	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	$R_{thJA}^{*4}$	-	62.5	-	°C/W

## •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Cumph of	Conditions	Value			Unit	
Parameter Symbol		Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	30	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	20.84	-	mV/°C	
Zero gate voltage drain current		V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	-	1	μA	
Gate - Source leakage current		$V_{GS}$ = ±20V, $V_{DS}$ = 0V	-	-	±10	μA	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient $\Delta V_{GS(th)}$ $\Delta T_j$		I <sub>D</sub> = 1mA referenced to 25°C	-	-3.25	-	mV/°C	
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 16A	-	3.5	4.5	m0	
on - state resistance	$R_{DS(on)}^{*5}$	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 16A	-	5.0	7.0	mΩ	
Forward Transfer  Y <sub>fs</sub>   <sup>*5</sup> N Admittance		V <sub>DS</sub> = 10V, I <sub>D</sub> = 8A	7.5	-	-	S	

\*1 Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L  $\simeq$  10µH, V\_{DD} = 15V, R\_G = 25\Omega, STARTING T\_{ch} = 25°C Fig.3-1,3-2

\*4 Mounted on a ceramic boad (30×30×0.8mm)

\*5 Pulsed

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## • Electrical characteristics ( $T_a = 25^{\circ}C$ )

Parameter	Sumbol	Conditions	Values			Unit	
	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2550	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15V	-	350	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	290	-		
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \simeq 15V, V_{GS} = 10V$	-	9	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 8A	-	30	-		
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ≃ 1.87Ω	-	80	-	ns	
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	45	-		

## • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Symbol Conditions		000	Values			Unit
Parameter			Min.	Тур.	Max.	Unit	
Total gata abarga	O *5		V <sub>GS</sub> = 10V	-	51	-	
Total gate charge	$Q_g^{*5}$	Q <sub>g</sub> <sup>o</sup> V <sub>DD</sub> ≃ 15V		-	25	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 16A	V <sub>GS</sub> = 4.5V	-	8	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5			-	10.5	-	

## •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Deremeter	Sumbol	Conditions	Values			Linit
	Parameter Symbol		Min.	Тур.	Max.	Unit
Continuous forward current	۱ <sub>S</sub> *1	$T = 25^{\circ}$	-	-	1.6	А
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	64	А
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.6A	_	-	1.2	V





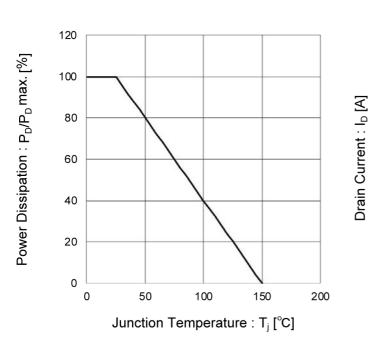
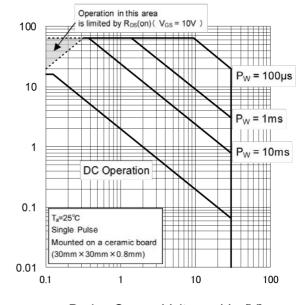


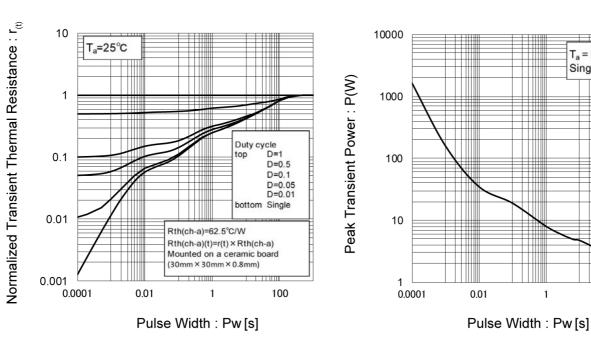
Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

## Fig.4 Single Pulse Maximum Power dissipation



100

1

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T<sub>a</sub> = 25°C Single Pulse

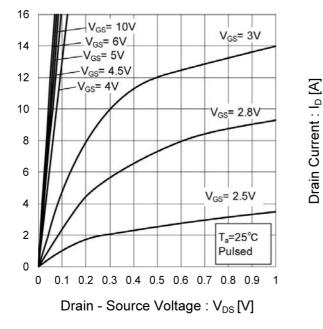
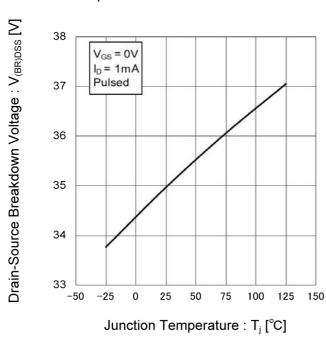
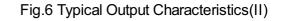
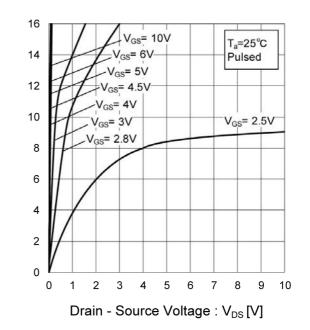


Fig.5 Typical Output Characteristics(I)

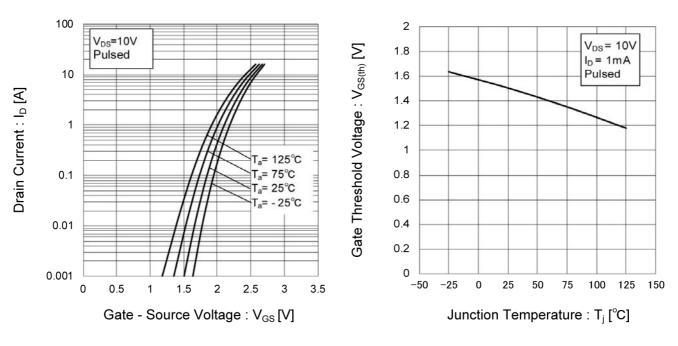
## Fig.7 Breakdown Voltage vs. Junction Temperature



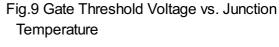




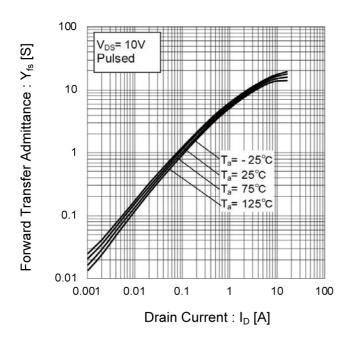




## Fig.8 Typical Transfer Characteristics



## Fig.10 Transconductance vs. Drain Current





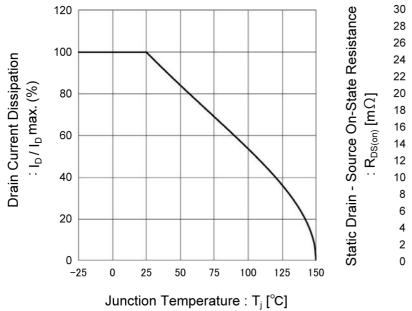
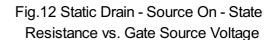


Fig.11 Drain Current Derating Curve



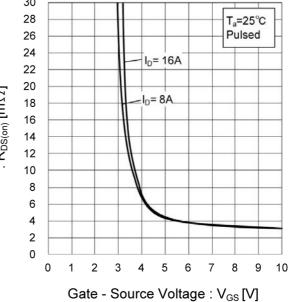
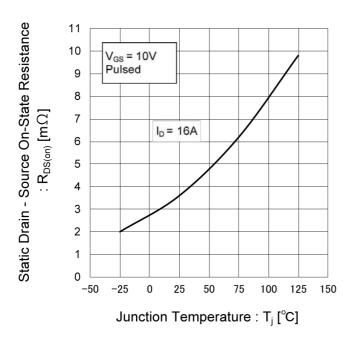


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





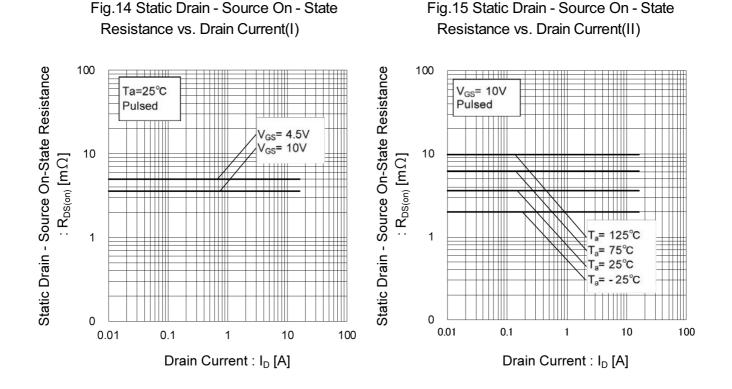
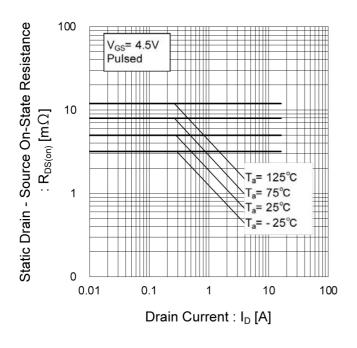


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)





Source Voltage

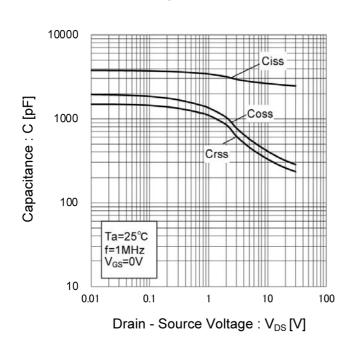


Fig.17 Typical Capacitance vs. Drain -

## Fig.18 Switching Characteristics

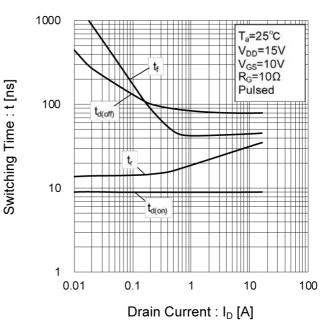
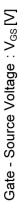


Fig.19 Dynamic Input Characteristics



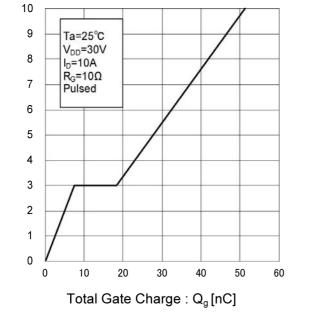
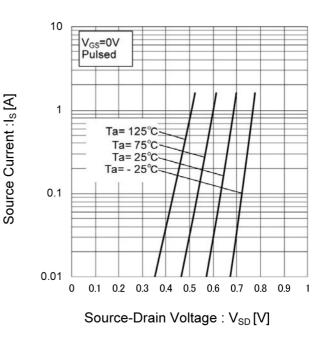


Fig.20 Source Current vs. Source Drain Voltage





### Measurement circuits

#### Fig.1-1 Switching Time Measurement Circuit

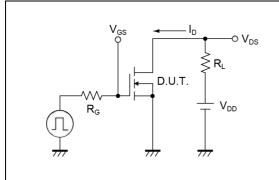
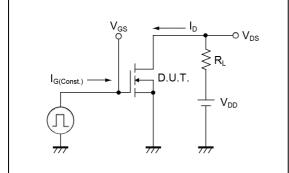
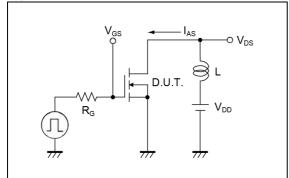


Fig.2-1 Gate Charge Measurement Circuit



#### Fig.3-1 AVALANCHE MEASUREMENT CIRCUIT



#### Fig.1-2 Switching Waveforms

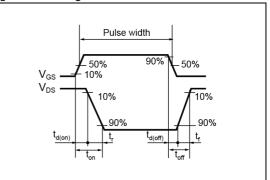
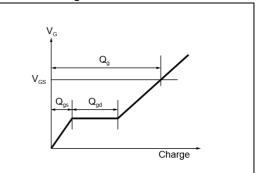
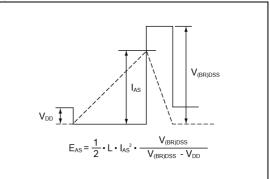


Fig.2-2 Gate Charge Waveform

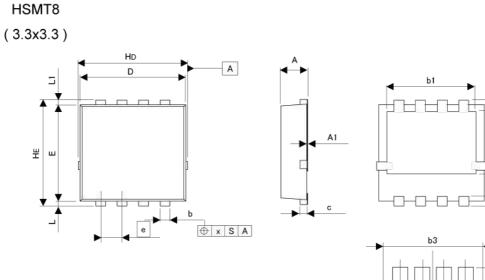


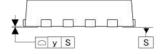
#### Fig.3-2 AVALANCHE WAVEFORM

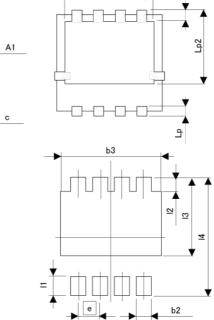




## Dimensions







5

Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIME	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
b1	2.50	2.70	0.098	0.106
с	0.10	0.30	0.004	0.012
D	3.10	3.30	0.122	0.130
E	2.90	3.10	0.114	0.122
е	0.65		0.0	26
HD	3.20	3.40	0.126	0.134
HE	3.20	3.40	0.126	0.134
L	0.07	0.25	0.003	0.010
L1	0.07	0.25	0.003	0.010
Lp	0.20	0.40	0.008	0.016
Lp1	0.25	0.45	0.010	0.018
Lp2	2.20	2.40	0.087	0.094
x	-	0.10	-	0.004
у	1991 (1991	0.10		0.004
	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	19 <u>1</u> 5	0.47		0.019
b3	370	2.70		0.106
11	(#)	0.50	1 H	0.020
12	140	0.55		0.022
13	2.75	2.40	×	0.094
19137		20.000		1

Dimension in mm/inches

14



0.134

3.40

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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## RQ3E160AD - Web Page

Part Number	RQ3E160AD
Package	HSMT8
Unit Quantity	3000
Minimum Package Quantity	3000
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes



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